



AF/ 28803  
REPLY UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2823  
PATENT 1  
3/11/03  
4/1/03  
VShaw

5298-02502/PM980196

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Sethuraman et al.

Serial No. 09/779,123

Filed: February 7, 2001

For: A PLANARIZED SEMICONDUCTOR  
INTERCONNECT TOPOGRAPHY  
AND METHOD FOR POLISHING A  
METAL LAYER TO FORM  
INTERCONNECT

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Group Art Unit: 2823

Examiner: Lee, H.

Atty. Dkt. No. 5298-02502

I hereby certify that this correspondence is being forwarded  
with sufficient postage as First-Class mail in an envelope addressed  
to: Commissioner for Patents, Box 28, Washington, DC 20231, on  
the date indicated below:

February 24, 2003

Date

Kevin L. Daffer

AMENDMENT: RESPONSE AFTER FINAL REJECTION PURSUANT TO 37 CFR § 1.116

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

Dear Sir/Madam:

This paper is submitted in response to the Office Action mailed December 31, 2002 to further  
highlight reasons why the application is in condition for allowance.

Please amend the case as follows.

IN THE CLAIMS

Please cancel claims 5, 6, 13, 14 and 16 without prejudice or disclaimer as to the subject matter  
recited therein. Please replace claims 1, 7, 9, 11, 15, and 17 with the amended claims below. A "marked-  
up" version of each amendment is included in **Attachment A**.